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Product Change Notification - JAON-13JEGV932 (Printer Friendly)

Date: 13 Jan 2016

Notification subject: CCB 1836 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 200K wafer technology available in 14L TSSOP package at MMT assembly site.

Notification text:

PCN Status:
Initial notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 14L TSSOP package at MMT assembly site.

Pre Change:
Gold (Au) or Palladium coated copper wire (PdCu) bond wire

Post Change:
Palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MMT assembly site	MMT assembly site
Wire material	Au wire or PdCu wire	CuPdAu wire
Die attach material	2200D	2200D
Molding compound material	G600V	G600V
Lead frame material	C7025	C7025

Impacts to Data Sheet:
None

Reason for Change:
To improve manufacturability by qualifying Palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:
In Progress

Estimated First Ship Date:
April 20, 2016 (date code: 1616)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Summary Table:

	January 2016				February 2016				March 2016					April 2016			
WW	01	02	03	04	05	06	07	08	09	10	11	12	13	14	15	16	17
Initial PCN Issue Date		X															
Qual Report Availability								X									
Final PCN Issue Date										X							
Implementation Date																X	

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Revision History:
January 13, 2016: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-13JEGV932_Qual_Plan.pdf
PCN_JAON-13JEGV932_Affected_CPN.pdf
PCN_JAON-13JEGV932_Affected_CPN.xls

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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